AOT42S60/AOTF42S60

600V 39A αMOS™ Power Transistor

General Description

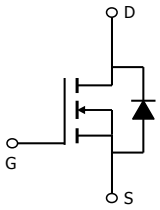
The AOT42S60 & AOTF42S60 have been fabricated using the advanced αMOS™ high voltage process that is designed to deliver high levels of performance and robustness in switching applications.

By providing low $R_{DS(on)}$, Q_g and E_{OSS} along with guaranteed avalanche capability these parts can be adopted quickly into new and existing offline power supply designs.

Features

V_{DS} @ $T_{j,max}$	700V
I_{DM}	166A
$R_{DS(ON),max}$	0.099Ω
$Q_{g,typ}$	40nC
E_{oss} @ 400V	9.2µJ

RoHS Compliant



Absolute Maximum Ratings T_A=25℃ unless otherwise noted						
Parameter		**Symbol**	**AOT42S60**	**AOTF42S60**	**AOTF42S60L**	**Units**
Drain-Source Voltage		V_{DS}	600			V
Gate-Source Voltage		V_{GS}	±30			V
Continuous Drain Current	T_C=25℃	I_D	39	39*	39*	A
	T_C=100℃		25	25*	25*	
Pulsed Drain Current [C]		I_{DM}	166			
Avalanche Current [C]		I_{AR}	11			A
Repetitive avalanche energy [C]		E_{AR}	234			mJ
Single pulsed avalanche energy [G]		E_{AS}	1345			mJ
Power Dissipation [B]	T_C=25℃	P_D	417	50	37.9	W
	Derate above 25°C		3.3	0.4	0.3	W/ °C
MOSFET dv/dt ruggedness		dv/dt	100			V/ns
Peak diode recovery dv/dt [H]			20			
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150			℃
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds [J]		T_L	300			℃
Thermal Characteristics						
Parameter		**Symbol**	**AOT42S60**	**AOTF42S60**	**AOTF42S60L**	**Units**
Maximum Junction-to-Ambient [A,D]		$R_{\theta JA}$	65	65	65	℃/W
Maximum Case-to-sink [A]		$R_{\theta CS}$	0.5	--	--	℃/W
Maximum Junction-to-Case		$R_{\theta JC}$	0.3	2.5	3.3	℃/W

* Drain current limited by maximum junction temperature.

Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250μA, V_{GS}=0V, T_J=25℃	600	-	-	V
		I_D=250μA, V_{GS}=0V, T_J=150℃	650	700	-	
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=600V, V_{GS}=0V	-	-	1	μA
		V_{DS}=480V, T_J=150℃	-	10	-	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±30V	-	-	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=5V,I_D=250μA	2.5	3.2	3.8	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=21A, T_J=25℃	-	0.085	0.099	Ω
		V_{GS}=10V, I_D=21A, T_J=150℃	-	0.24	0.28	Ω
V_{SD}	Diode Forward Voltage	I_S=21A,V_{GS}=0V, T_J=25℃	-	0.84	-	V
I_S	Maximum Body-Diode Continuous Current		-	-	39	A
I_{SM}	Maximum Body-Diode Pulsed Current		-	-	166	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=100V, f=1MHz	-	2154	-	pF
C_{oss}	Output Capacitance		-	135	-	pF
$C_{o(er)}$	Effective output capacitance, energy related [H]	V_{GS}=0V, V_{DS}=0 to 480V, f=1MHz	-	103	-	pF
$C_{o(tr)}$	Effective output capacitance, time related [I]		-	344	-	pF
C_{rss}	Reverse Transfer Capacitance	V_{GS}=0V, V_{DS}=100V, f=1MHz	-	2.7	-	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	-	1.7	-	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	V_{GS}=10V, V_{DS}=480V, I_D=21A	-	40	-	nC
Q_{gs}	Gate Source Charge		-	11.7	-	nC
Q_{gd}	Gate Drain Charge		-	11.9	-	nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=400V, I_D=21A, R_G=25Ω	-	38.5	-	ns
t_r	Turn-On Rise Time		-	53	-	ns
$t_{D(off)}$	Turn-Off DelayTime		-	136	-	ns
t_f	Turn-Off Fall Time		-	46	-	ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=21A,dI/dt=100A/μs,V_{DS}=400V	-	473	-	ns
I_{rm}	Peak Reverse Recovery Current	I_F=21A,dI/dt=100A/μs,V_{DS}=400V	-	38.5	-	A
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=21A,dI/dt=100A/μs,V_{DS}=400V	-	10.5	-	μC

A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with T_A=25℃.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150℃, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150℃, Ratings are based on low frequency and duty cycles to keep initial T_J =25℃.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150℃. The SOA curve provides a single pulse ratin g.
G. L=60mH, I_{AS}=6.7A, V_{DD}=150V, Starting T_J=25℃
H. $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$.
I. $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% $V_{(BR)DSS}$.
J. Wavesoldering only allowed at leads.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

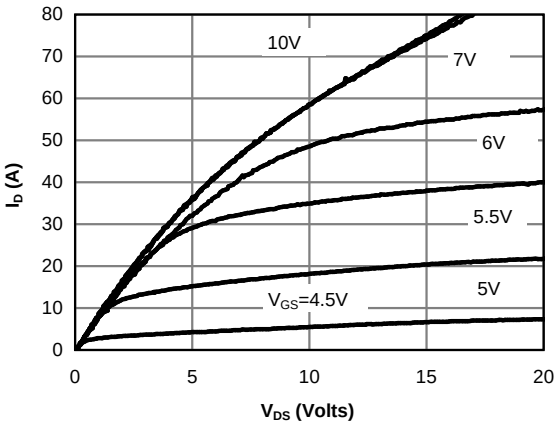


Figure 1: On-Region Characteristics@25℃

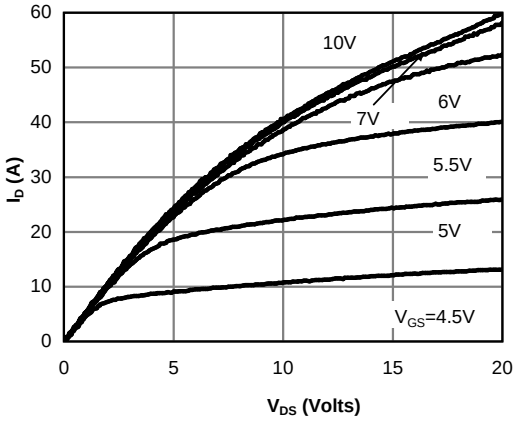


Figure 2: On-Region Characteristics@125℃

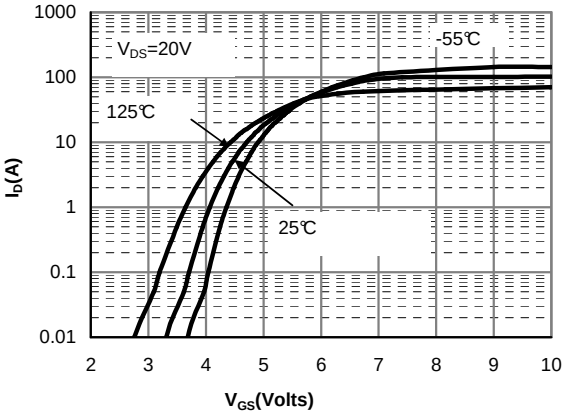


Figure 3: Transfer Characteristics

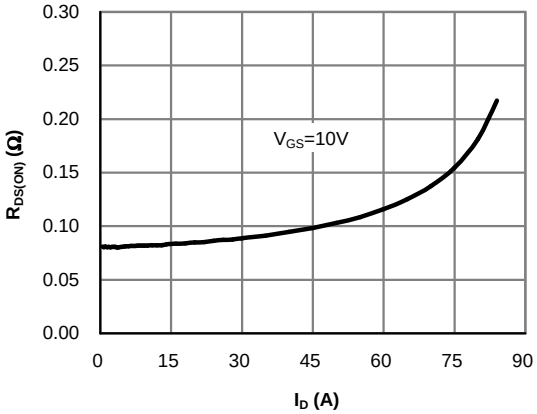


Figure 4: On-Resistance vs. Drain Current and Gate Voltage

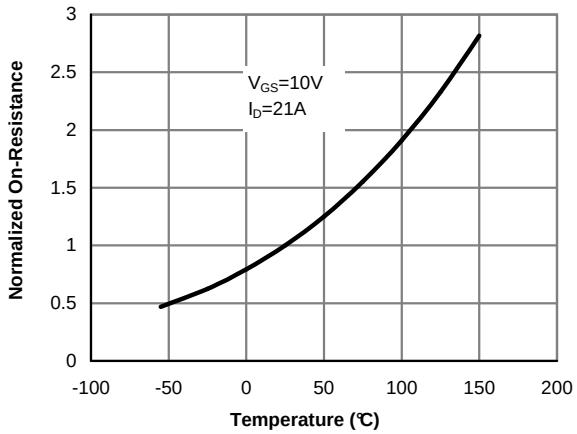


Figure 5: On-Resistance vs. Junction Temperature

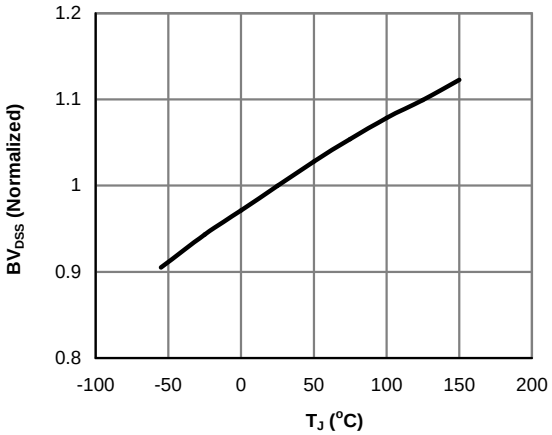


Figure 6: Break Down vs. Junction Temperature

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

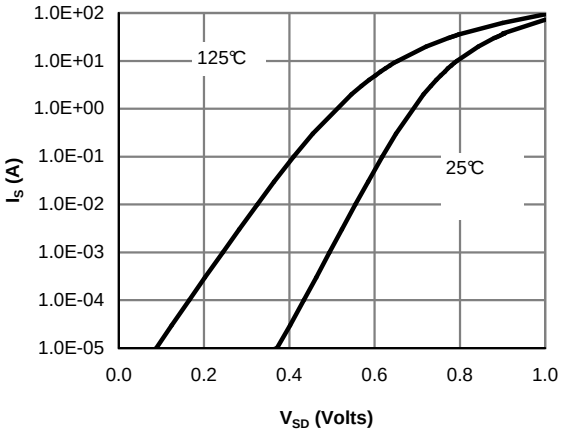


Figure 7: Body-Diode Characteristics (Note E)

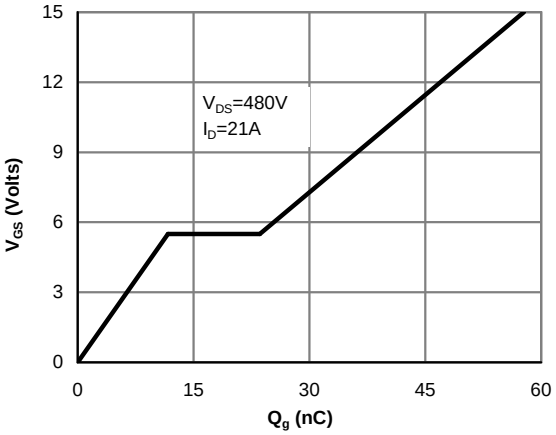


Figure 8: Gate-Charge Characteristics

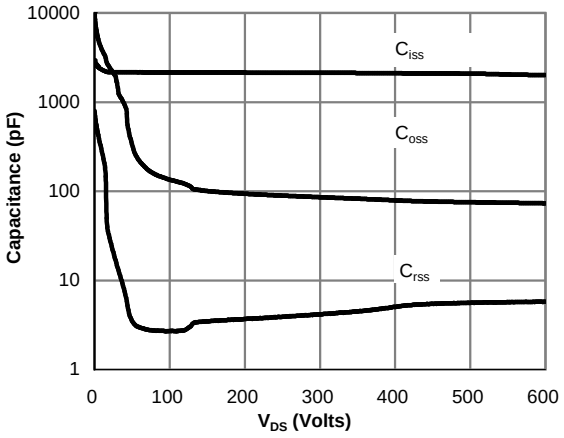


Figure 9: Capacitance Characteristics

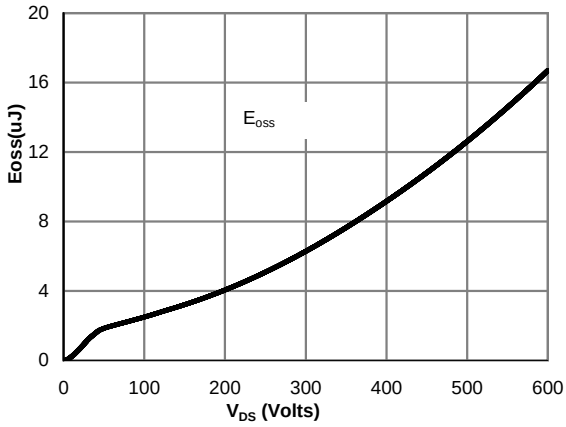


Figure 10: Coss stored Energy

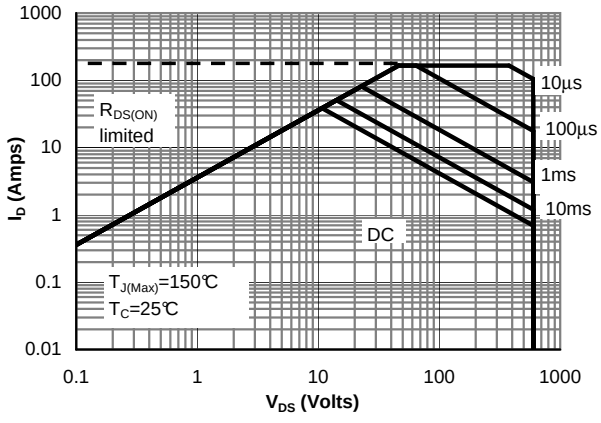


Figure 11: Maximum Forward Biased Safe Operating Area for AOT42S60(Note F)

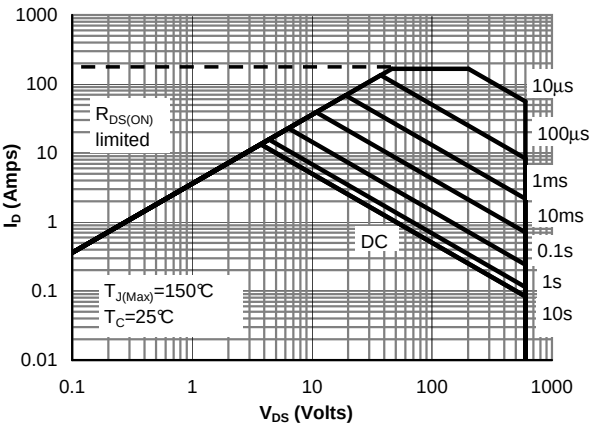


Figure 12: Maximum Forward Biased Safe Operating Area for AOTF42S60(Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

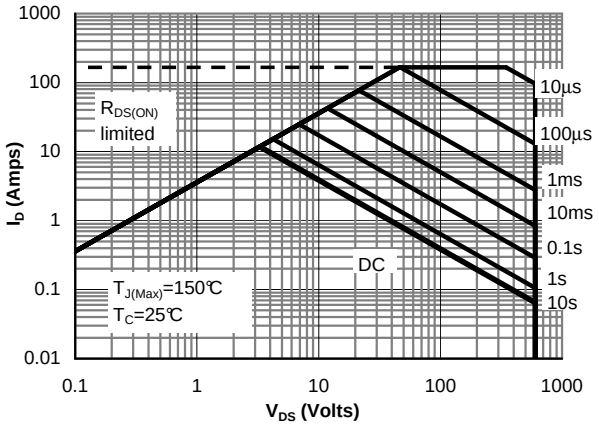


Figure 13: Maximum Forward Biased Safe Operating Area for AOTF42S60L(Note F)

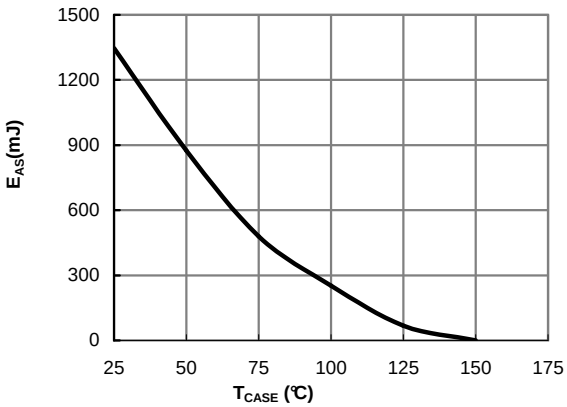


Figure 14: Avalanche energy

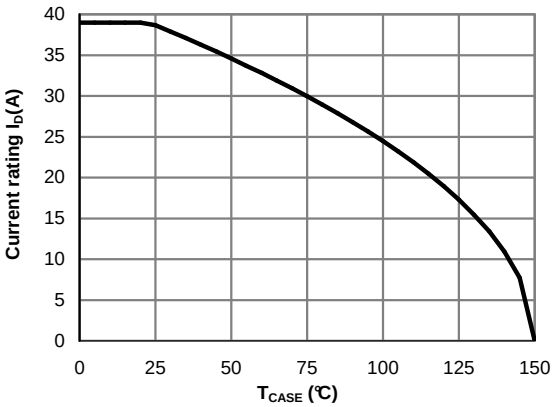


Figure 15: Current De-rating (Note B)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

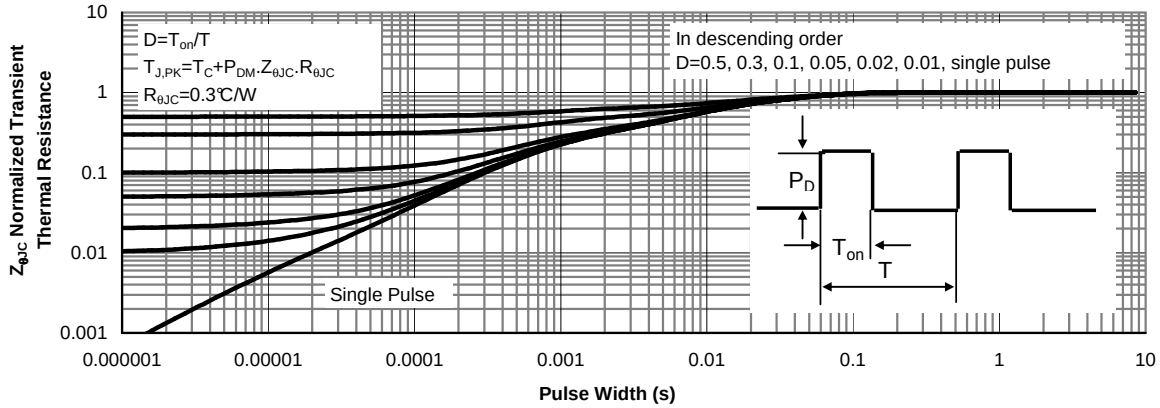


Figure 16: Normalized Maximum Transient Thermal Impedance for AOTF42S60(Note F)

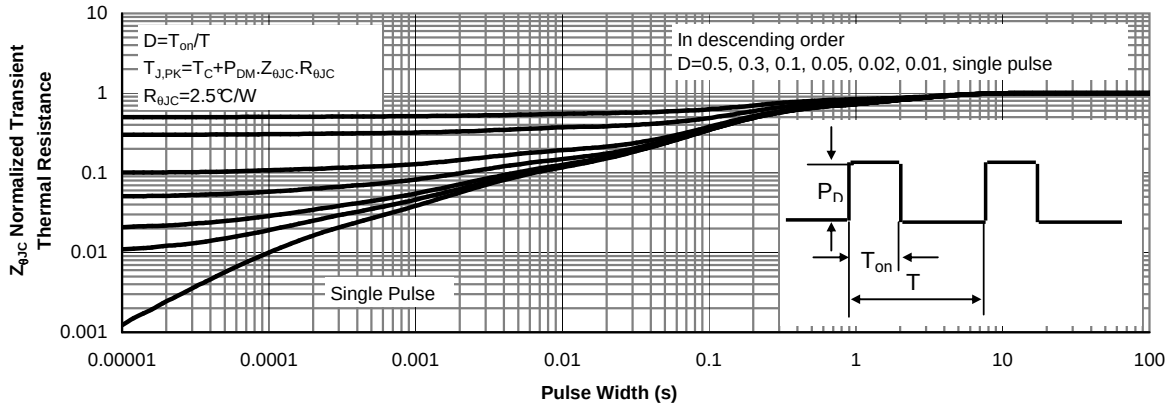


Figure 17: Normalized Maximum Transient Thermal Impedance for AOTF42S60(Note F)

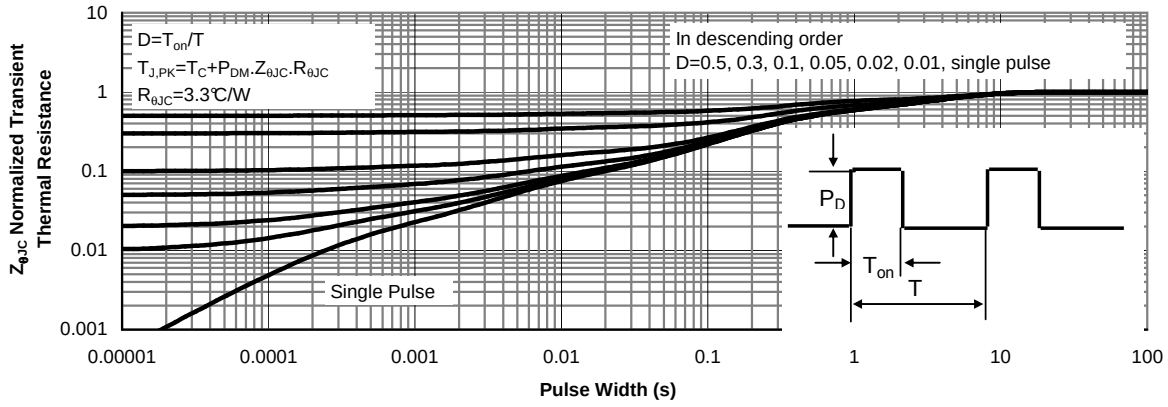
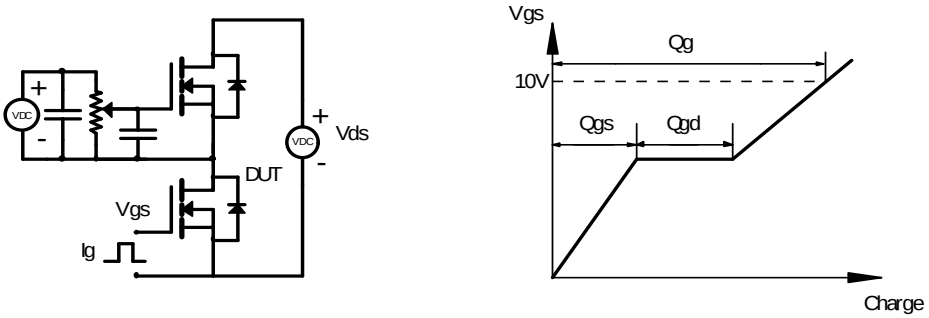
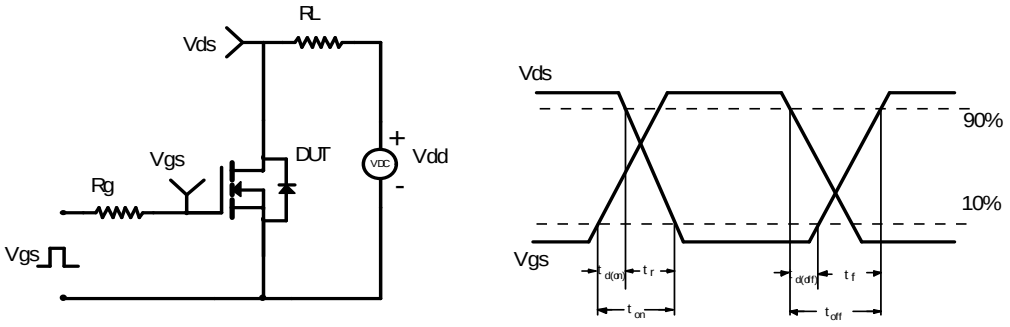


Figure 18: Normalized Maximum Transient Thermal Impedance for AOTF42S60L (Note F)

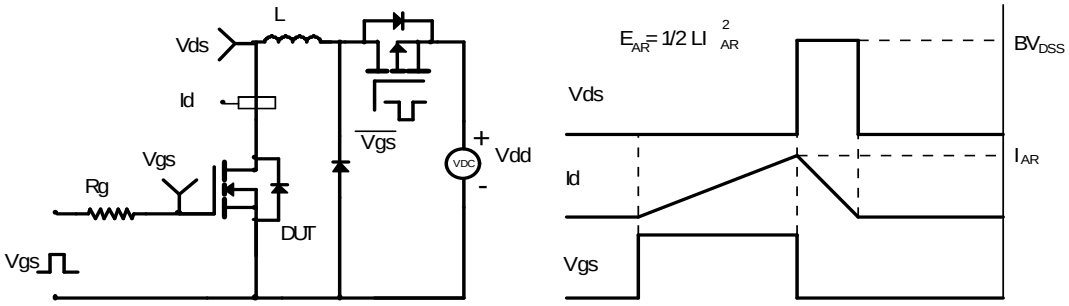
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms